



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	1.00	$\approx$	1.50	2
A <sub>1</sub>	0.25	0.30	0.40	
A <sub>2</sub>	0.75	0.90	1.10	
$\frac{D}{E}$	15.00 BSC			
$\frac{D}{E_1}$	13.60 BSC			
e	0.80 BSC			
$\phi_b$	0.40	0.45	0.50	
bbb	$\approx$	$\approx$	0.20	
ddd	$\approx$	$\approx$	0.20	
eee	$\approx$	$\approx$	0.15	
fff	$\approx$	$\approx$	0.08	
M	18			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994
2. SYMBOL "M" IS THE PIN MATRIX SIZE
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. THERE SHALL BE A MINIMUM CLEARANCE OF 0.25mm BETWEEN THE EDGE OF THE SOLDER BALL AND THE BODY EDGE
5. CONFORMS TO JEDEC MO-275-KKAB-1

PK381\_01\_111209

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.
11/23/09	1.1	Changed the orientation of the A1 ball pad corner indicator.

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.